



## **MacDermid Inc. Announces Breakthrough Additive Circuit Technology**

Waterbury, CT, January 2007 - MacDermid Electronics Solutions is proud to announce the release of MicroCat, a fully additive circuit formation process. MicroCat represents the synergy of two innovations: high resolution catalytic imaging, and high productivity additive metallization.

The two step MicroCat process results in solid copper circuit traces at a fraction of the cost of etched aluminum foil, etched copper foil, or silver PTF pastes and has demonstrated proven capability in RFID, smart card, membrane switch, and various other additive circuit applications.

The MicroCat process is available worldwide. With its wide operating window, MicroCat can be used in either manual or automated process equipment and on various flexible and rigid substrates. All printing technologies are suited for MicroCat processing.

MacDermid Electronics Solutions is a global specialty chemical and materials supplier serving the printed circuit board, semi-conductor packaging, lead frame, RFID, and flex circuitry markets. MacDermid Inc. was established in 1922 and has numerous R&D, manufacturing, sales, and technical support facilities worldwide. Visit MacDermid Electronics Solutions at [www.macdermid.com/electronics](http://www.macdermid.com/electronics)

For more information on MicroCat please contact Lisa Guerrero at 203-575-5743